



Board Manufacturing Specifications

Source Data From:

Project: HTLRBL32L-10 Breakout-30
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Obs.:

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Specifications		Complementary Details
PCB Name:	HTLRBL32L-10 Breakout Board	
Material:	Normal FR-4	
Size:	35 x 40.5 mm	
Quantity:	50	
Layers:	2	
Sides with Components:	1	
TG (°C):		
Thickness (mm):	1.6	
Min Track/Spacing (mil):	Other	0.5 mm
Min Hole Size:	Other	0.4 mm
Solder Mask:	Green	
Solder Mask Height Control:		
Silkscreen:	White	
Surface Finish:	HASL lead free	
Via Type:	Tenting Vias	
Blind Vias:	No	
Buried Vias:	No	
Via Anular Size:	Other	0.2 mm
BGA:	No	
Finished Cooper:	1 oz. Cu	
Other Specifications / Observations:		